Amendment to the Title:

Please amend the title as follows:

METHODS OF FORMING A PHOSPHORUS DOPED SILICON DIOXIDE COMPRISING SILICON DIOXIDE-COMPRISING LAYER

Amendments to the Specification:

Please amend paragraph [0004] as follows:

This invention includes methods of forming [0004] a phosphorus phosphorus doped silicon dioxide comprising layers, and methods of forming trench isolation in the fabrication of integrated circuitry. In one implementation, a method of forming a phosphorus doped silicon dioxide comprising layer includes positioning a substrate within a deposition chamber. First and second vapor phase reactants are introduced in alternate and temporally separated pulses to the substrate within the chamber in a plurality of deposition cycles under conditions effective to deposit a phosphorus doped silicon dioxide comprising layer on the substrate. One of the first and second vapor phase reactants is PO(OR)₃ where R is hydrocarbyl, and an other of the first and second vapor phase reactants is Si(OR)₃OH where R is hydrocarbyl.

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